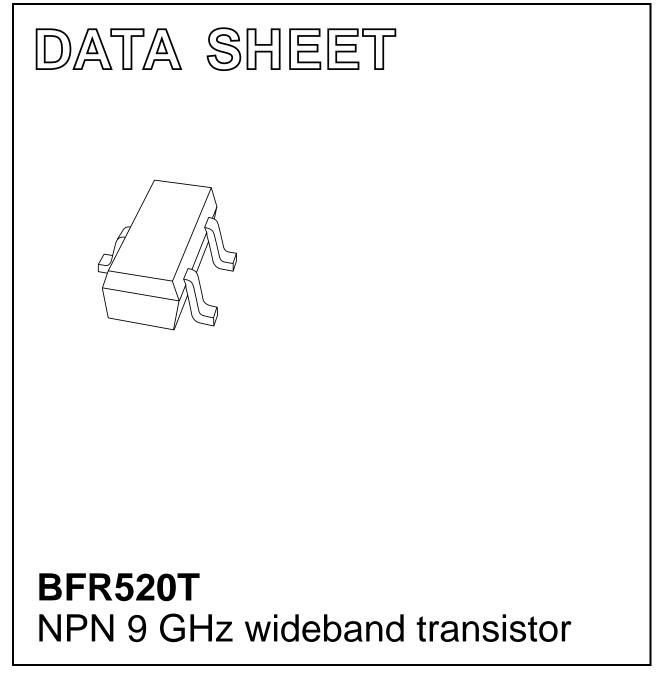
# DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 1999 Nov 02 2000 Apr 03



### FEATURES

- High power gain
- Low noise figure
- High transition frequency
- Gold metallization ensures
  excellent reliability
- SOT416 (SC-75) package.

### APPLICATIONS

Wideband applications such as satellite TV tuners, cellular phones, cordless phones, pagers etc., with signal frequencies up to 2 GHz.

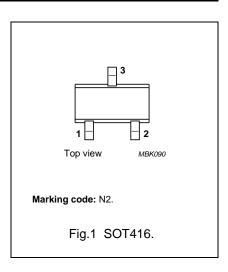
### QUICK REFERENCE DATA

### DESCRIPTION

Silicon NPN transistor encapsulated in a plastic SOT416 (SC-75) package.

### PINNING

PIN	DESCRIPTION	
1	base	
2	emitter	
3	collector	



SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	-	20	V
V <sub>CES</sub>	collector-emitter voltage	$R_{BE} = 0$	-	-	15	V
I <sub>C</sub>	DC collector current		-	-	70	mA
P <sub>tot</sub>	total power dissipation	up to $T_s = 75 \ ^{\circ}C$ ; note 1	-	-	150	mW
h <sub>FE</sub>	DC current gain	$I_{C} = 20 \text{ mA}; V_{CE} = 6 \text{ V}; T_{j} = 25 \text{ °C}$	60	120	250	
f <sub>T</sub>	transition frequency	$I_C = 20 \text{ mA}; V_{CE} = 6 \text{ V}; f = 1 \text{ GHz};$ $T_{amb} = 25 \text{ °C}$	-	9	-	GHz
G <sub>UM</sub>	maximum unilateral power gain	$I_{C} = 20 \text{ mA}; V_{CE} = 6 \text{ V}; f = 900 \text{ MHz};$ $T_{amb} = 25 \text{ °C}$	-	15	-	dB
F	noise figure	$I_{C}$ = 5 mA; $V_{CE}$ = 6 V; f = 900 MHz; $T_{amb}$ = 25 °C	-	1.1	1.6	dB

### Note

1.  $T_s$  is the temperature at the soldering point of the collector tab.

### LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	-	20	V
V <sub>CES</sub>	collector-emitter voltage	$R_{BE} = 0$	-	15	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	2.5	V
I <sub>C</sub>	DC collector current		-	70	mA
P <sub>tot</sub>	total power dissipation	up to $T_s = 75 \ ^{\circ}C$ ; note 1	-	150	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C

### Note

1.  $T_s$  is the temperature at the soldering point of the collector tab.

### **Product specification**

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### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R <sub>th j-s</sub>	thermal resistance from junction to soldering point	500	K/W

#### CHARACTERISTICS

 $T_j = 25 \ ^{\circ}C$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector cut-off current	I <sub>E</sub> = 0; V <sub>CE</sub> = 6 V	-	_	50	nA
h <sub>FE</sub>	DC current gain	I <sub>C</sub> = 20 mA; V <sub>CE</sub> = 6 V	60	120	250	
C <sub>e</sub>	emitter capacitance	$I_{C} = i_{c} = 0; V_{EB} = 0.5 V; f = 1 MHz$	-	1	-	pF
Cc	collector capacitance	I <sub>E</sub> = i <sub>e</sub> = 0; V <sub>CB</sub> = 6 V; f = 1 MHz	_	0.5	_	pF
C <sub>re</sub>	feedback capacitance	I <sub>C</sub> = 0; V <sub>CB</sub> = 6 V; f = 1 MHz	_	0.4	-	pF
f <sub>T</sub>	transition frequency	$I_{C}$ = 20 mA; V <sub>CE</sub> = 6 V; f = 1 GHz; T <sub>amb</sub> = 25 °C	-	9	-	GHz
G <sub>UM</sub>	maximum unilateral power gain; note 1	$I_C$ = 20 mA; V <sub>CE</sub> = 6 V; f = 900 MHz; T <sub>amb</sub> = 25 °C	-	15	-	dB
		$I_{C}$ = 20 mA; V <sub>CE</sub> = 6 V; f = 2 GHz; T <sub>amb</sub> = 25 °C	-	9	-	dB
s <sub>21</sub>   <sup>2</sup>	insertion power gain	$I_C$ = 20 mA; V <sub>CE</sub> = 6 V; f = 900 MHz; T <sub>amb</sub> = 25 °C	13	14	-	dB
F	noise figure	$\Gamma_{s} = \Gamma_{opt}$ ; I <sub>C</sub> = 5 mA; V <sub>CE</sub> = 6 V; f = 900 MHz; T <sub>amb</sub> = 25 °C	-	1.1	1.6	dB
		$\Gamma_{s} = \Gamma_{opt}$ ; I <sub>C</sub> = 20 mA; V <sub>CE</sub> = 6 V; f = 900 MHz; T <sub>amb</sub> = 25 °C	-	1.6	2.1	dB
		$\Gamma_{s} = \Gamma_{opt}$ ; I <sub>C</sub> = 5 mA; V <sub>CE</sub> = 6 V; f = 2 GHz; T <sub>amb</sub> = 25 °C	-	1.9	-	dB
P <sub>L1</sub>	output power at 1 dB gain compression	$I_{C}$ = 20 mA; V <sub>CE</sub> = 6 V; R <sub>L</sub> = 50 Ω; f = 900 MHz; T <sub>amb</sub> = 25 °C	-	17	_	dBm
ITO	third order intercept point	note 2	-	26	_	dBm

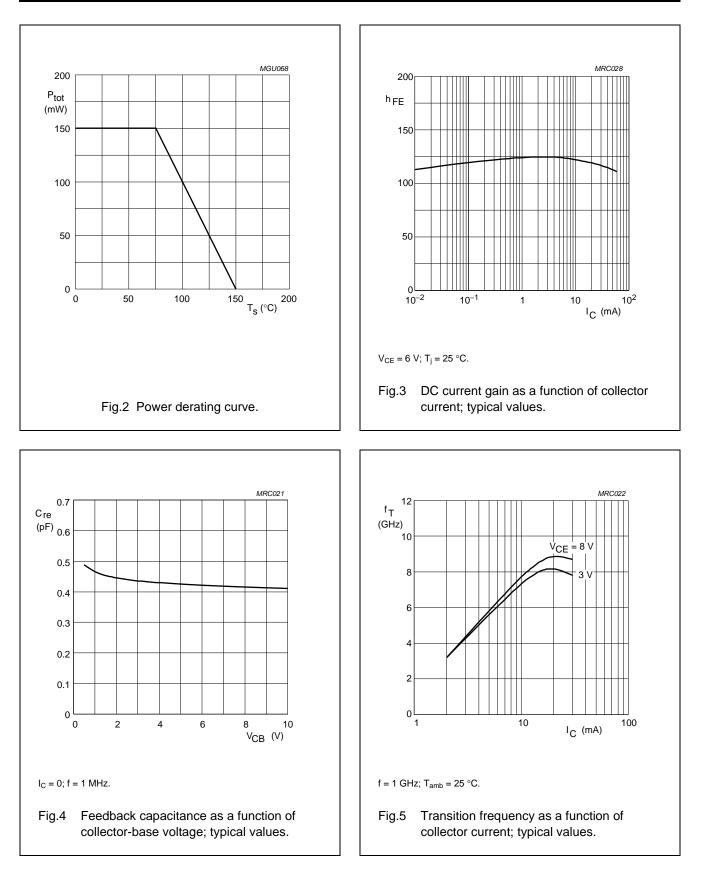
### Notes

1.  $G_{UM}$  is the maximum unilateral power gain, assuming  $s_{12}\, is$  zero and

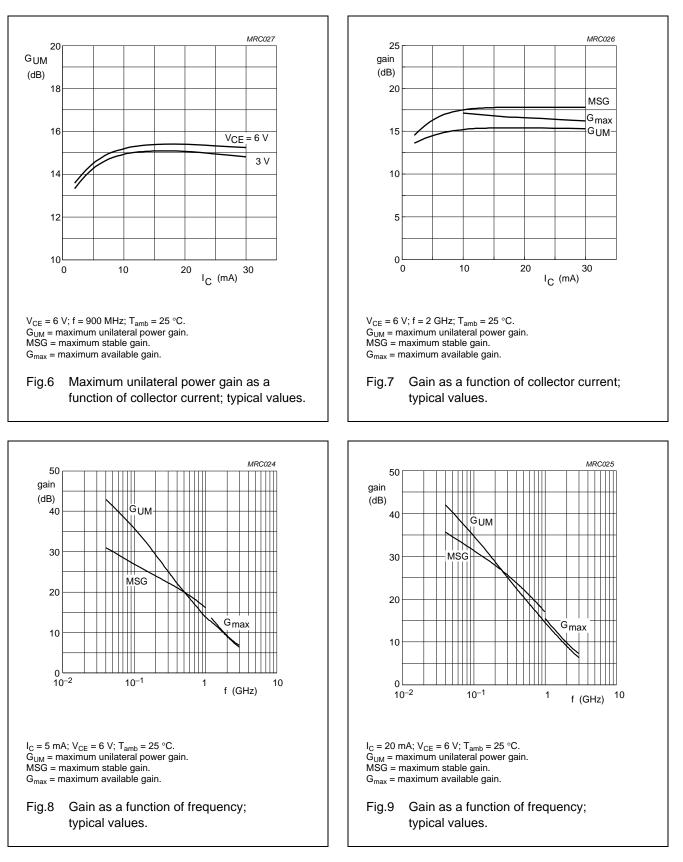
$$G_{UM} = 10 \log \frac{|s_{21}|^2}{(1 - |s_{11}|^2)(1 - |s_{22}|^2)} dB$$

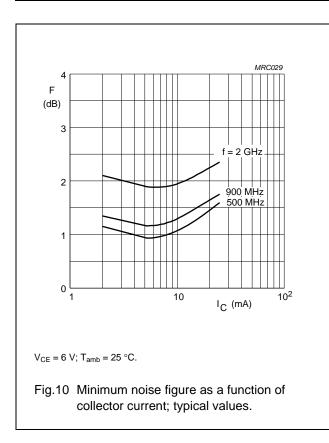
2.  $I_C = 20 \text{ mA}$ ;  $V_{CE} = 6 \text{ V}$ ;  $R_L = 50 \Omega$ ; f = 900 MHz;  $T_{amb} = 25 \text{ °C}$ ;  $f_p = 900 \text{ MHz}$ ;  $f_q = 902 \text{ MHz}$ ; measured at  $f_{(2p-q)} = 898 \text{ MHz}$  and at  $f_{(2q-p)} = 904 \text{ MHz}$ .

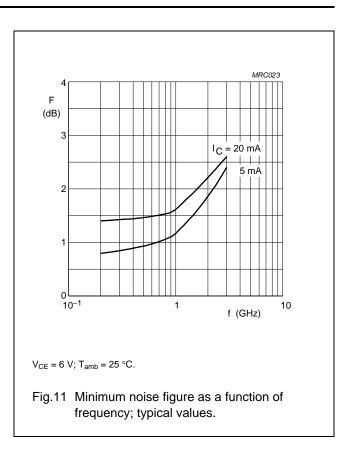
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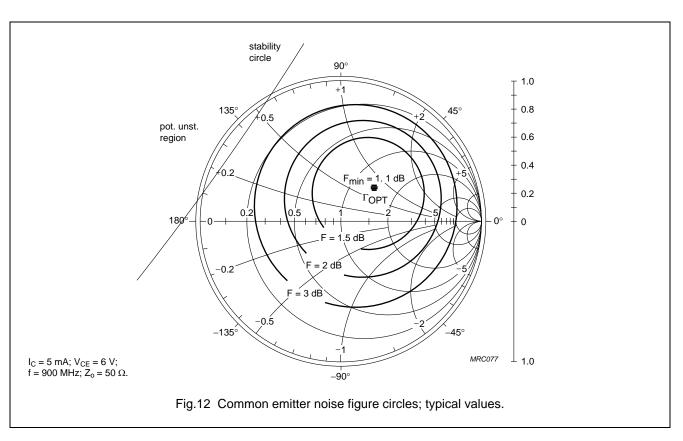


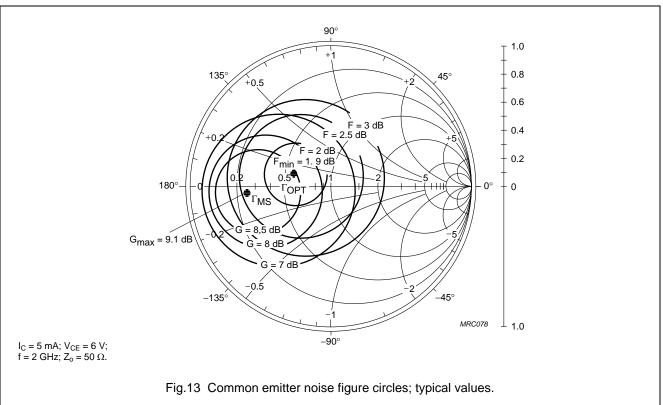
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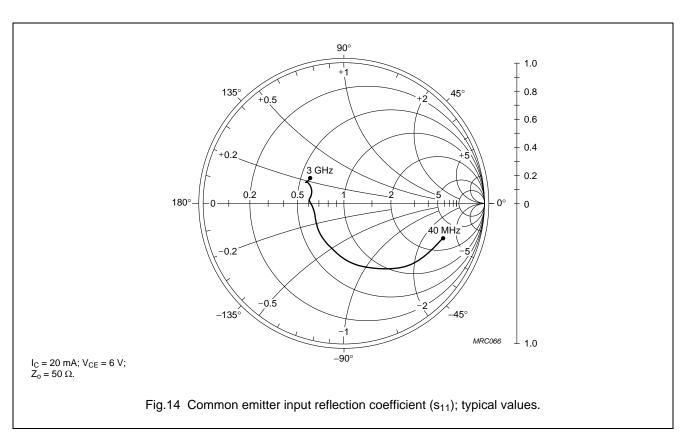


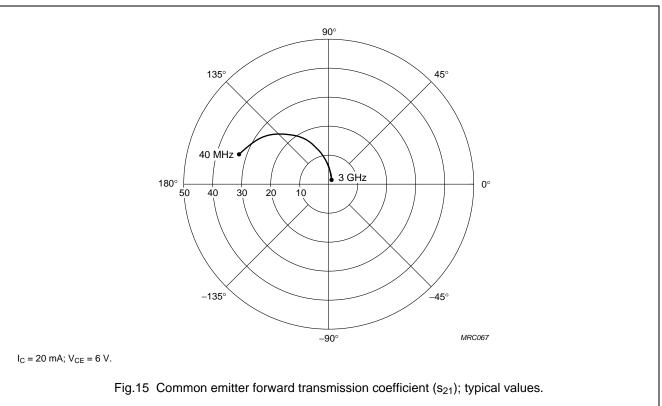


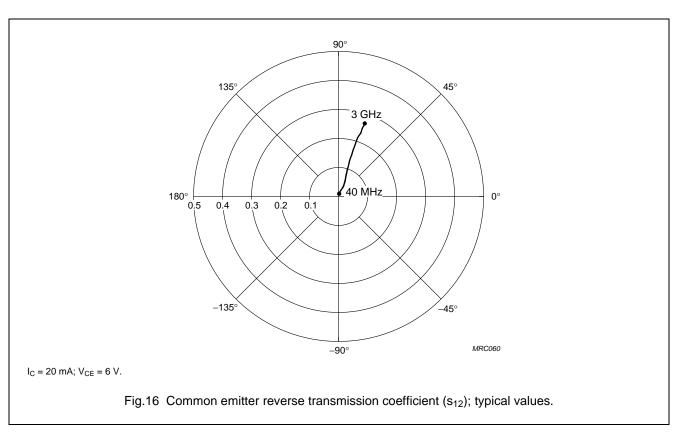


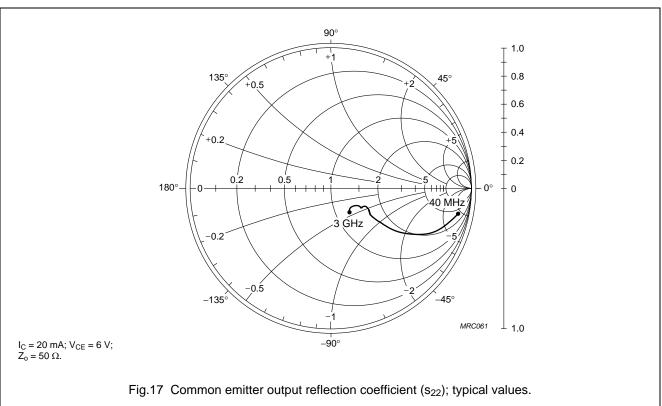








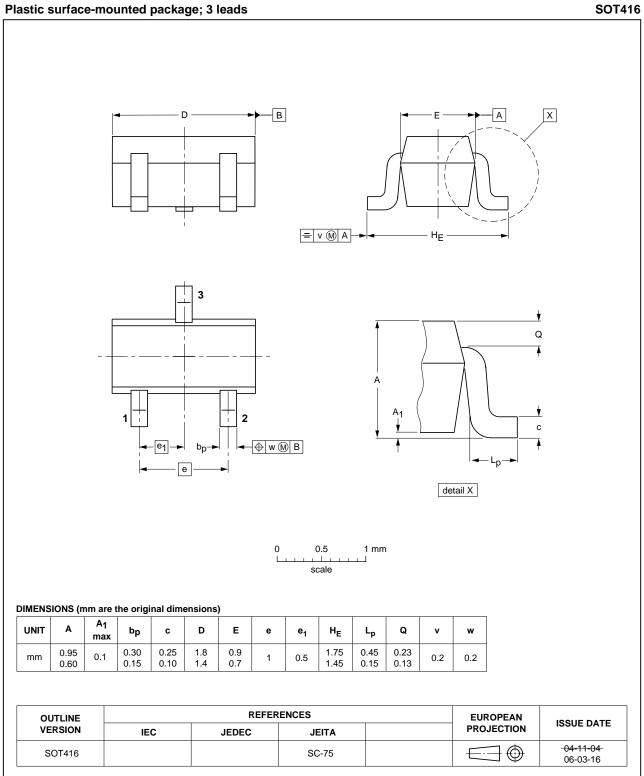




BFR520T

# NPN 9 GHz wideband transistor

### **PACKAGE OUTLINE**



### BFR520T

### DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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#### **Contact information**

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